

**AMENDMENTS TO THE CLAIMS**

**This listing of claims will replace all prior versions and listings of claims in the application:**

**LISTING OF CLAIMS:**

1. (Currently amended): A semiconductor integrated circuit comprising a microstrip structure comprising:

a signal line; and

a ground plate; and

another signal line disposed ~~close to the signal line and~~ on an opposite side of said ground plate as said signal line;

wherein at least one through hole is formed in said signal line, and an inner wall of said through hole is only directly electrically connected to said signal line,

wherein an aperture size of said through hole is smaller than a width of said signal line.

2. (Currently amended): A semiconductor integrated circuit comprising a microstrip structure comprising:

a signal line;

a ground plate; and

another signal line disposed ~~close to the signal line and~~ on an opposite side of said ground plate as said signal line;

wherein at least one through hole is formed in said ground plate, and an inner wall of said through hole is only directly electrically connected to said ground plate,  
wherein an aperture size of said through hole is smaller than a width of said signal line.

Claims 3 and 4 (canceled).

5. (Currently amended): A semiconductor integrated circuit comprising a microstrip structure comprising:

a signal line;

a ground plate; and

another signal line disposed ~~close to the signal line and~~ on an opposite side of said ground plate as said signal line;

wherein at least one through hole is formed in said signal line, and an inner wall of said through hole which is formed in said signal line is only directly electrically connected to said signal line, and

wherein at least one through hole is formed in said ground plate, and an inner wall of said through hole which is formed in said ground plate is only directly electrically connected to said ground plate.

Claims 6-8 (canceled)

9. (Currently amended): ~~A semiconductor integrated circuit comprising a signal transmission line of a microstrip structure comprising a signal line and a ground plate according to claim 1, A semiconductor integrated circuit comprising a microstrip structure comprising:~~  
a signal line;  
a ground plate; and  
another signal line disposed on an opposite side of said ground plate as said signal line;  
wherein, ~~instead of at least one hole formed in said signal line or in said ground plate,~~ a plurality of slit holes are formed by forming said signal line or said ground plate of a plurality of thin strips and by connecting the thin strips at respective terminal ends of the thin strips, and an inner wall of said plurality of slit holes is only directly electrically connected to said signal line.

10. (currently amended): A semiconductor integrated circuit comprising a microstrip structure comprising:  
a signal line;  
a ground plate; and  
~~another signal line disposed close to the signal line and on an opposite side of the ground plate as said signal line;~~

wherein ~~at least one through hole is a plurality of through holes~~ are formed in said signal line and an inner wall of said ~~through hole~~ plurality of through holes is directly electrically connected to said signal line, and ~~said at least one through hole comprises a~~

wherein, said plurality of through holes are formed along a longitudinal direction of a signal transmission line and arranged at equal spaces or in a same pattern.

11. (currently amended): A semiconductor integrated circuit comprising a microstrip structure comprising:

a signal line;

a ground plate; and

another signal line disposed ~~close to the signal line and~~ on an opposite side of the ground plate as said signal line;

wherein ~~at least one through hole is a plurality of through holes~~ are formed in said signal line ground plate and an inner wall of said ~~through hole~~ is plurality of through holes is directly electrically connected to said signal line ground plate, and ~~said at least one through hole comprises a~~

wherein, said plurality of through holes are formed along a longitudinal direction of a signal transmission line and arranged at equal spaces or in a same pattern.

AMENDMENT UNDER 37 C.F.R. § 1.116  
U.S. Application No.: 09/664,094

Attorney Docket No.: Q60884

12. (canceled)